

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	((("6054762") or ("6627384") or ("3429029") or ("5676855")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/11/23 17:10
L2	0	L1 and clean\$4	USPAT	ADJ	ON	2009/11/23 17:10
L3	17303	(chemical near3 clean\$4 or etch\$4) same (hydrogen adj peroxide or sodium adj persulfate or "H.sub.2O.sub.2" or "Na.sub.2S.sub.2O.sub.8")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/23 17:15
L4	3213	(chemical near3 clean\$4 or etch\$4) same (cu or copper) same (hydrogen adj peroxide or sodium adj persulfate or "H.sub.2O.sub.2" or "Na.sub.2S.sub.2O.sub.8")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/23 17:16
L5	1534	(chemical near3 clean\$4 or etch\$4) same (cu or copper) same (hydrogen adj peroxide or sodium adj persulfate or "H.sub.2O.sub.2" or "Na.sub.2S.sub.2O.sub.8") and (chemical near3 clean\$4 or etch\$4) with (resist or mask\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/23 17:17
L6	949	(chemical near3 clean\$4 or etch\$4) same (cu or copper) same (hydrogen adj peroxide or sodium adj persulfate or "H.sub.2O.sub.2" or "Na.sub.2S.sub.2O.sub.8") and (chemical near3 clean\$4 or etch\$4) with (resist or mask\$4) and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/23 17:17

S1	1	"5981036".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/11 12:04
S2	1	"3744120".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/11 12:28
S3	1	"10506611"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 07:43
S4	0	"0862209".pn.	EPO	ADJ	ON	2008/03/14 10:17
S5	3	("5379942").PN. OR ("5981036").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 10:43
S6	0	schulz-harden.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:38
S7	0	harden-jurgen.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:39
S8	569	harden.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:40
S9	0	harden-jurgen-schulz.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:42
S10	0	harder-jurgen-schulz.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:42
S11	42	schulz-harder-jurgen.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/14 13:43
S12	46317	(braz\$4 or solder\$4 or weld\$4) near5 resist\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 08:37
S13	2273	((braz\$4 or solder\$4 or weld\$4) near5 resist\$4) same (coat\$4 or layer or film or foil) and (ceramic near5 substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 08:39
S14	570	((((braz\$4 or solder\$4 or weld\$4) near5 resist\$4) same (coat\$4 or layer or film or foil)) and ((ceramic near5 substrate) same (metal near5 (coat\$4 or layer or film or foil)))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 08:41

S15	375	((braz\$4 or solder\$4 or weld\$4) near5 resist\$4) same (coat\$4 or layer or film or foil) and ((ceramic near5 substrate) same (metal near5 (coat\$4 or layer or film or foil))) not resistor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 08:45
S16	345	((braz\$4 or solder\$4 or weld\$4) near5 resist\$4) same (coat\$4 or layer or film or foil) and ((ceramic near5 substrate) same (metal near5 (coat\$4 or layer or film or foil))) not (resistor or "resistance welding")	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 08:48
S17	33	((braz\$4 or solder\$4 or weld\$4) near5 resist\$4) same (coat\$4 or layer or film or foil) and ((ceramic near5 substrate) same (metal near5 (coat\$4 or layer or film or foil))) not (resistor or "resistance welding" or resistance or resistant)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 09:23
S18	246	((braz\$4 or solder\$4 or weld\$4) near5 resist) same (coat\$4 or layer or film or foil) and ((ceramic near5 substrate) same (metal near5 (coat\$4 or layer or film or foil)))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/17 09:24
S19	7	"4946709".pn. or "20020027018".pn. or "20030070839".pn. or "20020104877".pn. or "5747875".pn. or "4862323".pn. or "20020060091".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 08:09
S20	6	("4946709".pn. or "20020027018".pn. or "20030070839".pn. or "20020104877".pn. or "5747875".pn. or "4862323".pn. or "20020060091".pn.) and resist\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 08:16
S23	7123	Miyahara.in.	JPO	ADJ	ON	2008/03/19 10:08
S24	350	Miyahara.in. and "2001".py.	JPO	ADJ	ON	2008/03/19 10:09
S27	7893	((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution same (etch\$4 or clean\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 10:26
S28	290	((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution) same (etch\$4 or clean\$4) and ((ceramic near5 substrate) same (metal or foil))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 10:29

S29	20	((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution) same (etch\$4 or clean\$4) same ((ceramic near5 substrate) same (metal or foil))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 10:29
S30	17	((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution) same (etch\$4 or clean\$4) same ((ceramic near5 substrate) same (metal or foil)) and resist\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 10:38
S31	10	(US-20060022020-\$ or US-20020104877-\$ or US-20030068532-\$).did. or (US-5981036-\$ or US-6297469-\$ or US-4862323-\$ or US-4946709-\$).did. or (US-3438874-\$ or US-3529350-\$ or US-3846166-\$).did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 11:39
S32	1	S31 and (solder resist)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 11:40
S33	5	S31 and (epox\$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 11:43
S34	0	(epox\$4 near5 resist) same (ceramic near5 metal) and (etch\$4 or clean\$4) with (((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:28
S35	0	(epox\$4 near5 resist) same (ceramic near5 metal) and (etch\$4 or clean\$4) same (((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:29
S36	0	(epox\$4 near5 resist) near100 (ceramic near5 metal) and (etch\$4 or clean\$4) near100 (((hydrogen near5 peroxide) or (sodium near5 persulfate)) near5 solution)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:30
S37	0	(epox\$4 near5 resist) near100 (ceramic near5 metal) and (etch\$4 or clean\$4) near100 ((hydrogen near5 peroxide) or (sodium near5 persulfate))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:30
S38	16	(epox\$4 near5 resist) and (ceramic near5 metal) and (etch\$4 or clean\$4) and ((hydrogen near5 peroxide) or (sodium near5 persulfate))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:31

S39	9	S38 and (cured or curing or cures or cure)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 13:59
S40	5	S38 and ((cured or curing or cures or cure) near10 (heat\$3 or therm\$5))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 14:00
S41	10	(US-20060022020-\$ or US-20020104877-\$ or US- 20030068532-\$).did. or (US-5981036-\$ or US- 6297469-\$ or US-4862323-\$ or US-4946709-\$).did. or (US-3438874-\$ or US-3529350-\$ or US-3846166-\$). did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 14:57
S42	1	S41 and optic\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 14:57
S43	5668	(ceramic near5 metal near5 substrate) and etch\$4 and (layer or coat or foil or film)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 15:44
S44	687	228/122.1.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 15:53
S45	56	228/122.1.ccls. and (metal near5 ceramic near5 substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 15:54
S46	1	"20030068532".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:30
S47	1	"20030068532"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:30
S48	1	"20030068532"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:30
S49	0	"10108317"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:32
S50	88	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and (metal near5 ceramic near5 substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:37
S51	32	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and (metal near5 ceramic near5 substrate) not S45	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:37

S52	484	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and etch\$4 and (layer or coat or foil or film)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:41
S53	269	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and etch\$4 and (layer or coat or foil or film) and substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:42
S54	200	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and etch\$4 and (layer or coat or foil or film) and substrate and @py<="2003"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/19 16:45
S55	2	(228/122.1.ccls. or 228/123.1.ccls. or 228/193.ccls. or 228/194.ccls. or 228/201.ccls. or 228/202.ccls. or 228/215.ccls.) and etch\$4 and resist with (plural\$4 or multipl\$4 or many or several)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/20 10:40
S56	48	("228".clas.) and etch\$4 and resist with (plural\$4 or multipl\$4 or many or several)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/20 11:02
S57	37	(228/159.ccls. or 228/199.ccls. or 228/215.ccls.) and etch\$4 and resist	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/20 15:24
S58	976	(228/159.ccls. or 228/199.ccls. or 228/215.ccls.)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/20 15:25
S59	95	copper same foil same resist same ceramic	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 09:05
S60	112	copper same foil same resist same ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:05

S61	14	lorengo and thin with film same circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:33
S62	74	mltf	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:41
S63	8	mltf and etch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:42
S64	15	mltf and etch\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:42
S65	2	"5258236".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:51
S66	2	"5213140".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:55

S67	2	"5243140".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 09:56
S68	11	mltf and (resist or mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/24 10:02
S69	2171	resist same cure same (heat or therm\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:17
S70	95	(braz\$4 or solder\$4) adj resist same cure same (heat or therm\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:18
S71	1	(braz\$4) adj resist same cure same (heat or therm\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:18
S72	1	((braz\$4 or solder\$4) adj resist same cure same (heat or therm\$4)) and optic\$5 near20 read\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:26
S73	11	((braz\$4 or solder\$4) adj resist same cure same (heat or therm\$4)) and optic\$5	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:27
S74	11	(US-20060022020-\$ or US-20040212030-\$).did. or (US-5981036-\$ or US-6297469-\$ or US-4946709-\$ or US-5756377-\$ or US-5525204-\$ or US-6225035-\$ or US-6036809-\$).did. or (US-3529350-\$ or US-3429029-\$).did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:53
S75	2	S74 and ((braz\$4 or solder\$4) adj resist same cure same (heat or therm\$4))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 10:54
S76	1	"4622058".pn. and mask	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 12:13
S77	72	S69 and (optic\$4 near10 device)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 12:55

S78	0	S69 and (optic\$4 near10 device near20 readable)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 12:56
S79	0	S69 and (optic\$4 near10 device near20 code)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 12:57
S80	64	S69 and (optic\$4 near10 device) and substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 13:10
S81	18	S69 and (optic\$4 near10 device) and substrate same ceramic	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 13:11
S82	1194	substrate with ceramic same metal same (layer or foil or coat\$4) same optic\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:10
S83	15	substrate with ceramic same metal same (layer or foil or coat\$4) same optic\$4 and "228".clas.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:10
S84	5	(US-5981036-\$ or US-5756377-\$ or US-4622058-\$). did. or (US-3429029-\$ or US-3268653-\$).did.	USPAT; USOCR	ADJ	ON	2008/03/24 14:16
S85	0	S84 and optic\$5	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:16
S86	11	(US-20060022020-\$ or US-20040212030-\$).did. or (US-5981036-\$ or US-6297469-\$ or US-4946709-\$ or US-5756377-\$ or US-6036809-\$ or US-4622058-\$). did. or (US-3529350-\$ or US-3429029-\$ or US- 3268653-\$).did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:17
S87	2	S86 and optic\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:17
S88	8	substrate with ceramic same metal same (layer or foil or coat\$4) same (bar code)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:23
S89	9	substrate with ceramic same metal same (layer or foil or coat\$4) same (bar code or barcode)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:23
S90	0	substrate with ceramic same metal same (layer or foil or coat\$4) same resist same (bar code or barcode)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/24 14:25

S91	153	metal near5 ceramic with (board or circuit or chip or substrate) same ((braz\$4 or solder\$4) near5 resist\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 16:10
S92	66	("4420652" "4991582" "5287076" "5333095" "5434358" "5470345" "5620476" "5650759" "5683435" "5685632" "5735884" "5750926" "5751539" "5759197" "5782891" "5825608" "5836992" "5866851" "5867361" "5870272" "5896267" "5905627" "5959829" "5973906" "5999398" "6008980" "6275369").PN. OR ("6414835").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/04/28 16:45
S93	21	metal near5 ceramic with (cu or copper) with (board or circuit or chip or substrate) same ((braz\$4 or solder\$4) near5 resist\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 12:47
S94	1246	direct near5 copper near5 bond\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:13
S95	380	direct adj copper adj bond\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:13

S96	0	(direct adj copper adj bond\$4) same braz\$4 same ceramic same ((braz\$4 or solder\$4) near5 resist\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:14
S97	26	(direct adj copper adj bond\$4) same braz\$4 same ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:14
S98	1	(direct adj copper adj bond\$4) same braz\$4 with (resist\$4 or mask\$3) same ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:17
S99	1	(direct adj copper adj bond\$4) same braz\$4 same ceramic and braz\$4 with (resist\$4 or mask\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:18
S100	15	(direct adj copper adj bond\$4) same braz\$4 same ceramic and (resist\$4 or mask\$4 or etch\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 13:21
S101	1	("4884334").PN.	USPAT; USOCR	OR	OFF	2009/04/30 14:03

S102	160	ultrasonic near3 horn same transducer same horn same tool	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 14:05
S103	645	braz\$4 near4 resist\$4 same (structur\$4 or etch\$4 or mask\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 14:16
S104	11	braz\$4 near4 resist\$4 same (structur\$4 or etch\$4 or mask\$4) and ((hydrogen near3 peroxide) or (sodium near3 persulfate) or (copper near3 chloride) or (iron near3 chloride))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/30 14:24
S105	1	("5676855").PN.	USPAT; USOCR	OR	OFF	2009/05/06 11:05
S106	27	("5474957" "5578525" "5602059").PN. OR ("5756377").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 11:49
S107	23	S106 and (resist\$4 or etch\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 11:49
S108	676	(dcb or direct near5 (copper or bond\$4)) same (cu or copper) same ceramic and (resist\$4 or mask\$4) same (etch\$4 or resist\$4 or remov\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 12:00
S109	193	(dcb or direct near5 (copper or bond\$4)) same (cu or copper) same ceramic and (resist\$4 or mask\$4) with (braz\$4 or solder\$4) same (etch\$4 or resist\$4 or remov\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 12:01

S110	195	(dcb or direct near5 (copper or bond\$4)) same (cu or copper) same ceramic and (resist\$4 or mask\$4) with (braz\$4 or solder\$4) same (etch\$4 or resist\$4 or remov\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/12 12:02
S111	699	(dcb or direct near5 (copper or bond\$4)) same (cu or copper) same ceramic and (resist\$4 or mask\$4) same (etch\$4 or resist\$4 or remov\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/12 12:02
S112	23	("4882454" "4963697" "5258887" "5321210" "5347091").PN. OR ("5917157").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 13:32
S113	12	S112 and (cu or copper) same (etch\$4 or remov\$4 or resist\$4 or mask\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 13:33
S114	10	S113 and (resist\$4 or photoresist\$4 or mask\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 13:49
S115	46	(dcb or direct near5 (copper or bond\$4)) same (cu or copper) same ceramic and (resist or resisting or photoresist or mask\$4) with (braz\$4 or solder\$4) same (etch\$4 or resist or resisting or photoresist or remov\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/12 14:00
S116	19	("3883947" "4358748" "5200026" "5302492" "5354415" "5377406" "5800726" "6015505" "6183883" "6197435" "6223429" "6475401" "6706622").PN. OR ("6918529").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:04
S117	19	S116 and (cu or copper or resist or photoresist or mask\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:07
S118	12	S116 and (cu or copper or resist or photoresist or mask\$4) and (resist or photoresist or mask\$4) near5 (solder\$4 or braz\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:08

S119	11	S116 and (cu or copper) and (resist or photoresist or mask\$4) near5 (solder\$4 or braz\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:18
S120	23	S106 and (resist or etch\$4 or photoresist or mask\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:28
S121	22	S106 and (resist or etch\$4 or photoresist or mask\$4) and (cu or copper)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/12 15:32
S122	11	(US-20020167064-\$).did. or (US-5616230-\$ or US-5917157-\$ or US-4882454-\$ or US-6670216-\$ or US-5321210-\$ or US-6054762-\$ or US-3883947-\$ or US-5354415-\$ or US-5302492-\$ or US-5377406-\$).did.	US-PGPUB; USPAT	ADJ	ON	2009/11/12 16:02
S123	11	S122 and (cu or copper) and (resist or photoresist or mask\$4 or etch\$4) and (cu or copper or braz\$4 or solder\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/12 16:03
S124	10462	216/13,17,41,49,33,36,83,96,100,105.ccls. or 29/846,847.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 09:25
S125	0	ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 09:27
S126	61	S124 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 09:27
S127	18	S124 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) and (braz\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 09:50
S128	0	brazing resist same photoresist	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 10:17
S129	1	(braz\$4 near3 resist) same (photoresist or photo resist or photo-resist)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 10:18
S130	196	epoxy with base\$2 with resist same (photoresist or photo\$1resist)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 10:19
S131	7	S124 and S130	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 10:19

S132	20	S124 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) with direct\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 10:36
S133	6004	S124 and (many or two or several or plural or plurality or more or multiple or multiplicity) same etch\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 11:03
S134	3099	S124 and (many or two or several or plural or plurality or more or multiple or multiplicity) same etch\$4 same (resist\$4 or photo\$4resist\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 11:03
S135	3099	S124 and (many or two or several or plural or plurality or more or multiple or multiplicity) same etch\$4 same (resist\$4 or photo\$1resist\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 11:03
S136	1509	S124 and (many or two or several or plural or plurality or more or multiple or multiplicity) same etch\$4 same (resist\$4 or photo\$1resist\$4) and etch\$4 same (cu or copper)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 11:04
S137	660	438/734.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 11:45
S138	0	S137 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) with direct\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 11:46
S139	550	438/734.ccls. and etch	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 11:46
S140	643	438/734.ccls. and etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 11:46

S141	34	S124 and S137	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 11:47
S142	34	S124 and S137 and etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 11:47
S143	1	("5490627").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/11/17 12:20
S144	180	438/734.ccls. and etch\$4 and (copper or cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 12:29
S145	165	S144 not S142	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/17 12:29
S146	6	(US-4657778-\$ or US-4413766-\$ or US-6858151-\$ or US-6696224-\$ or US-6696222-\$ or US-5858877-\$). did.	USPAT	ADJ	ON	2009/11/17 12:51
S147	673	S144 or S142 or S140 or S132 or S130 or S126 or S127	USPAT	ADJ	ON	2009/11/17 13:25
S148	13	S147 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) and (etch\$4 or mask\$4 or resist\$4 or photo\$1resist\$4) same (grind\$4 or polish\$4 or clean\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:26

S149	1	S147 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) with direct and (etch\$4 or mask\$4 or resist\$4 or photo\$1resist\$4) same (grind\$4 or polish\$4 or clean\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:29
S150	11071	S124 or S140	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:31
S151	1	S150 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) with direct and (etch\$4 or mask\$4 or resist\$4 or photo\$1resist\$4) same (grind\$4 or polish\$4 or clean\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:31
S152	1	S150 and ceramic with (copper or cu) with (bond\$4 or join\$4 or joint\$4) with direct and (etch\$4 or mask\$4 or resist\$4 or photo\$1resist\$4) same (grind\$4 or polish\$4 or clean\$4 or scrub\$4 or brush\$4 or abrad\$4 or abras\$4)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:33
S153	11	(cu or copper) with ((pretreat\$5 or pre\$1treat\$5) near10 (clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5)) near20 (before or prior) near20 (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:35
S154	3	("20020041023" "20040159913" "20050029640"). PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:39
S155	3	("20020041023" "20040159913" "20050029640"). PN. and (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:41
S156	3	("20020041023" "20040159913" "20050029640"). PN. and (clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:42
S157	887	(cu or copper) with (clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5) same (before or prior) with (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:50

S158	22	(cu or copper) with ((pretreat\$5 or pre\$1treat\$5) with (clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5)) same (before or prior) with (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:51
S159	887	(cu or copper) with ((clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5)) same (before or prior) with (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:54
S160	415	(cu or copper) with ((clean\$5 or scrub\$5 or grind\$5 or brush\$5 or abrad\$5 or abras\$5)) with (before or prior) with (etch\$5 or resist\$4 or photo\$1resist\$4 or mask\$5)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/17 13:54
S161	47	(US-20060022020-\$ or US-20030056981-\$ or US-20020167064-\$).did. or (US-5981036-\$ or US-6297469-\$ or US-4946709-\$ or US-5756377-\$ or US-6036809-\$ or US-4622058-\$ or US-5578162-\$ or US-6001517-\$ or US-6015520-\$ or US-4775786-\$ or US-4456679-\$ or US-5880403-\$ or US-6238741-\$ or US-6414835-\$ or US-6660116-\$ or US-5508089-\$ or US-5676855-\$ or US-6324072-\$ or US-5616230-\$ or US-5917157-\$ or US-4882454-\$ or US-6670216-\$ or US-5321210-\$ or US-6054762-\$ or US-3883947-\$ or US-5354415-\$).did. or (US-5302492-\$ or US-5377406-\$ or US-4657778-\$ or US-4413766-\$ or US-6858151-\$ or US-6696224-\$ or US-6696222-\$ or US-5858877-\$ or US-4987677-\$ or US-3921022-\$ or US-5037482-\$).did. or (US-3529350-\$ or US-3429029-\$ or US-3268653-\$).did. or (JP-2001118960-\$ or JP-2001185664-\$).did. or (EP-221010-\$ or EP-868961-\$).did.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	ADJ	ON	2009/11/19 11:15
S162	2	S161 and (peel\$4 near\$4 strength)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/19 11:15

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